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(12) **United States Design Patent**
Wada

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(54) **SEMICONDUCTOR MODULE**

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(**) Term: **15 Years**

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(22) Filed: **Sep. 3, 2020**

(30) **Foreign Application Priority Data**

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(51) **LOC (13) Cl.** **13-03**

(52) **U.S. Cl.**
USPC **D13/182**

(58) **Field of Classification Search**
USPC D13/123, 133, 146, 147, 158, 182, 184, D13/199
CPC H01F 17/06; H01F 27/02; H01R 4/00; H01R 4/20; H01R 4/24; H01R 4/2429; H01R 4/50; H01R 4/70; H01R 9/05; H01R 13/46; H01R 13/65; H01L 27/08; H01L 27/07; H01L 27/06; H01L 25/07; H01L 25/16; H01L 25/18; H01L 23/00; H01L 23/31; H05K 7/00; H05K 7/20; H02M 7/00
See application file for complete search history.

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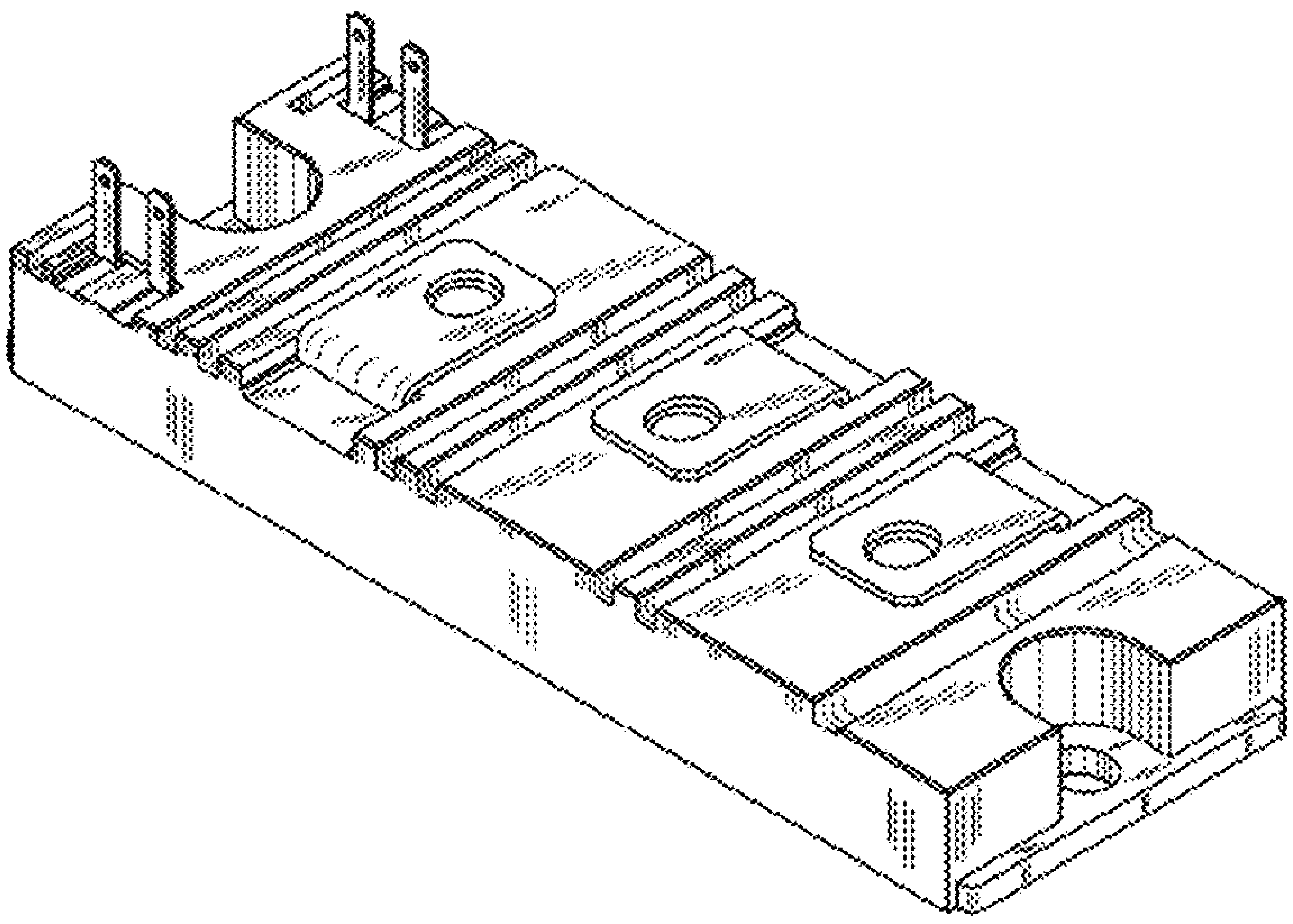
(57) **CLAIM**

I claim the ornamental design for a semiconductor module, as shown and described.

DESCRIPTION

FIG. **1** is a front view of a semiconductor module according to the present invention.
FIG. **2** is a top view of the semiconductor module of FIG. **1**.
FIG. **3** is a left side view of the semiconductor module of FIG. **1**.
FIG. **4** is a rear side view of the semiconductor module of FIG. **1**.
FIG. **5** is a bottom view of the semiconductor module of FIG. **1**.
FIG. **6** is a right side view of the semiconductor module of FIG. **1**; and,
FIG. **7** is a front, top and right side perspective view of the semiconductor module of FIG. **1**.

1 Claim, 3 Drawing Sheets



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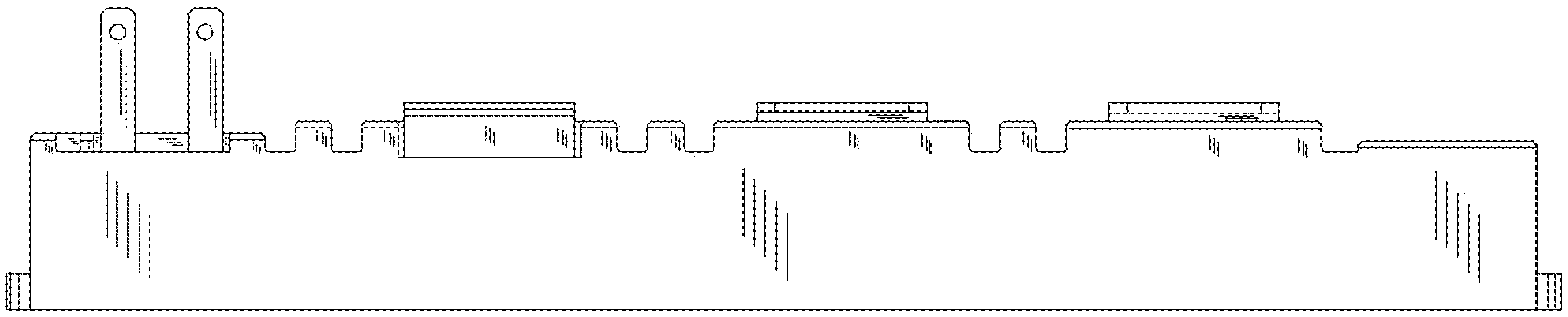

Fig.1

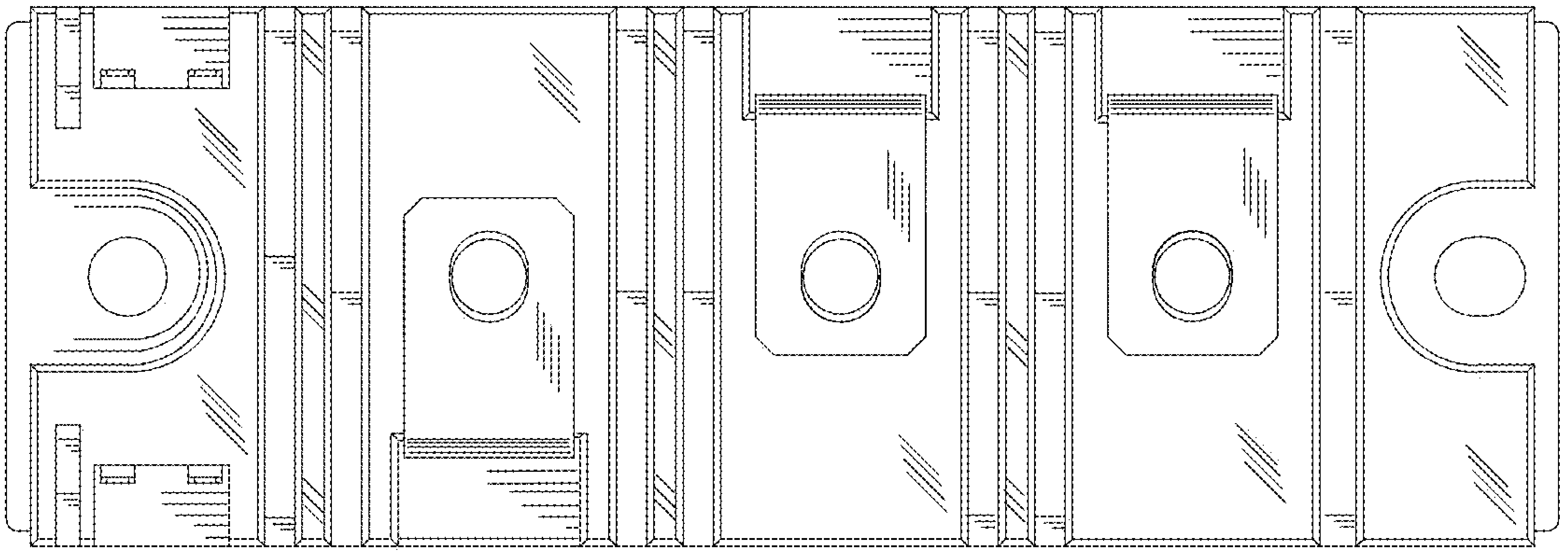

Fig.2

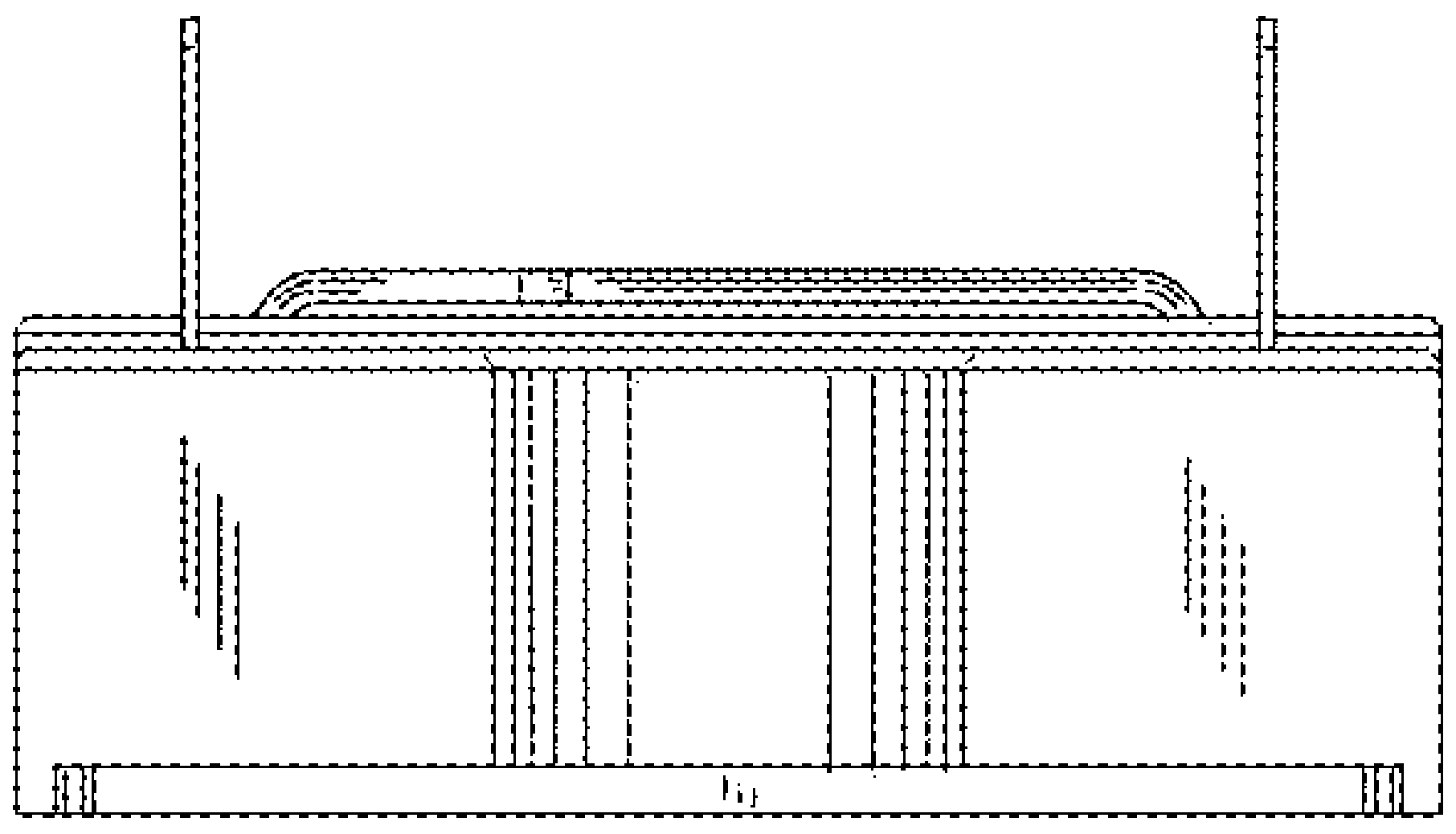

Fig.3

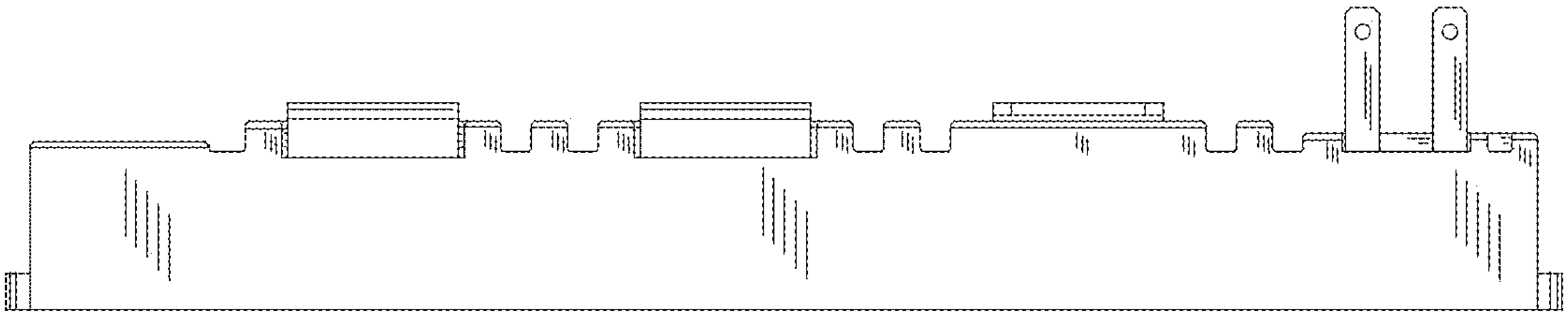

Fig.4

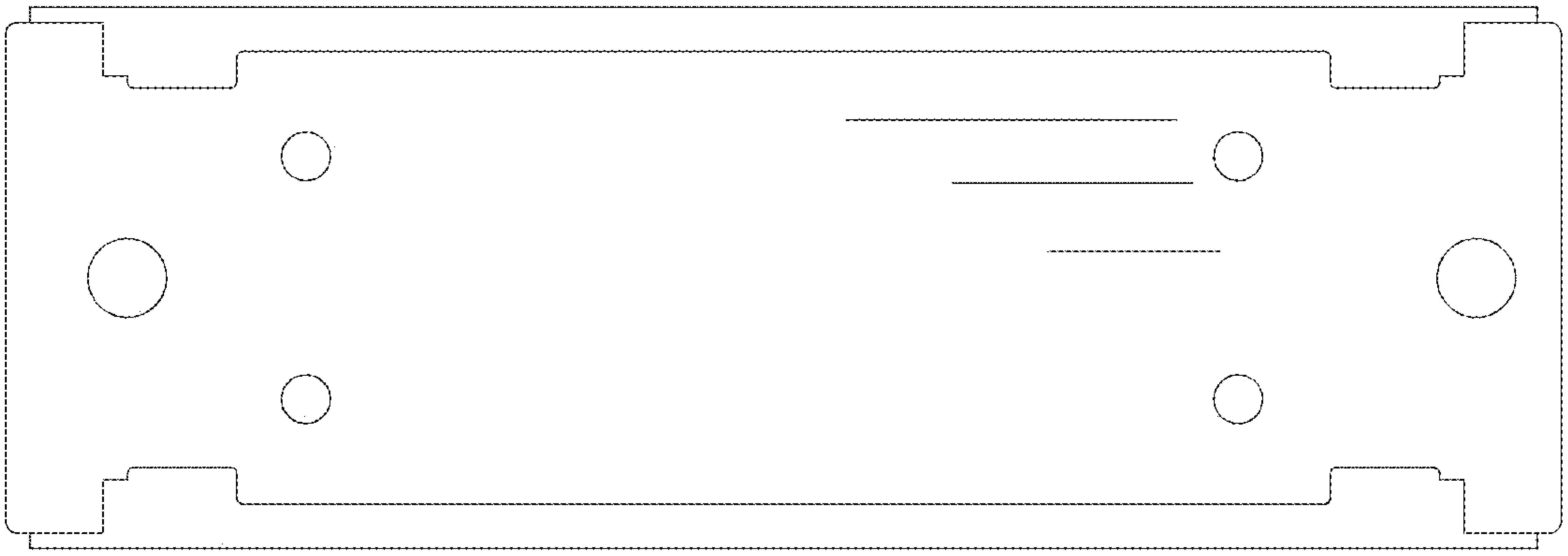

Fig.5

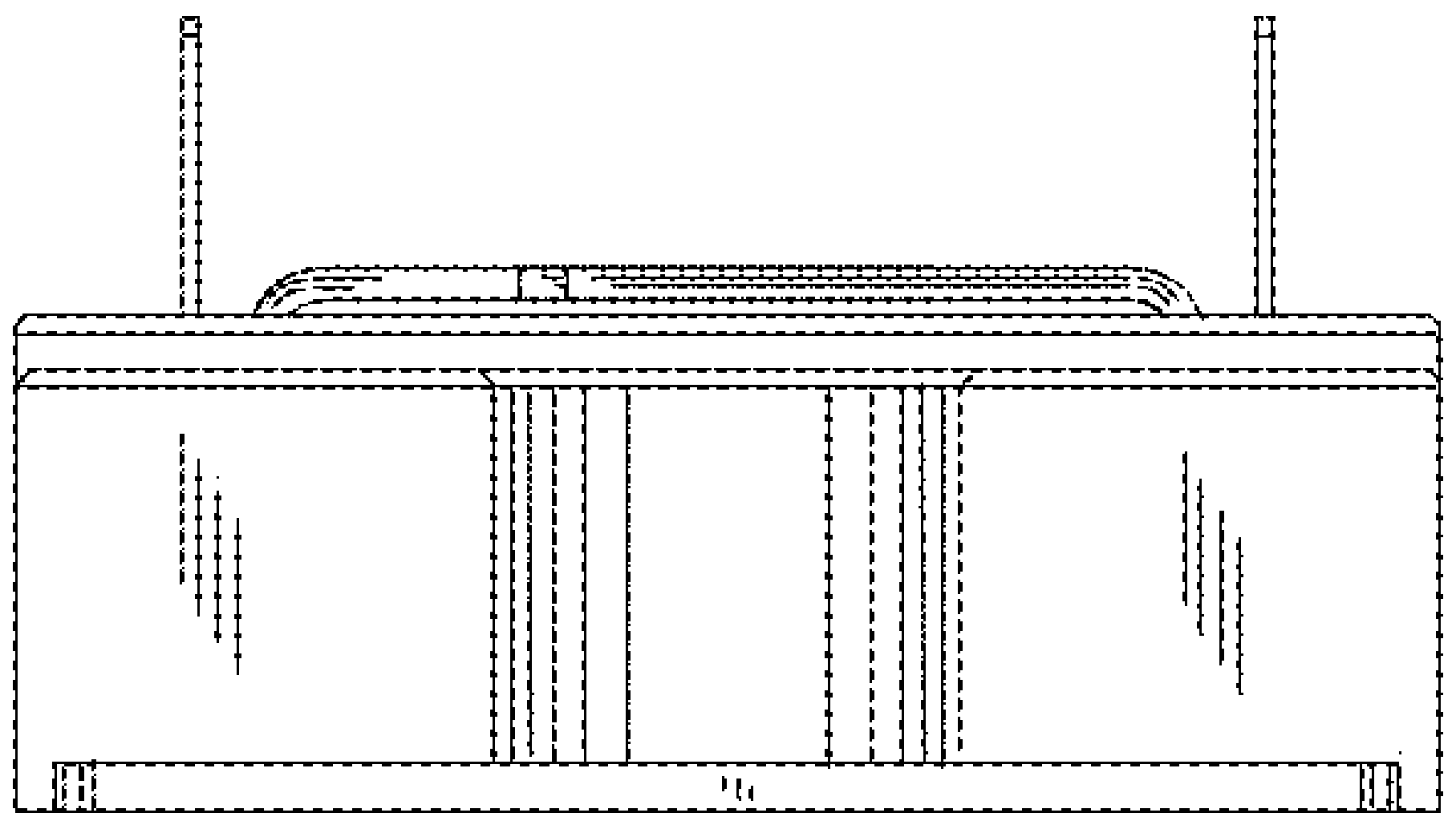

Fig.6

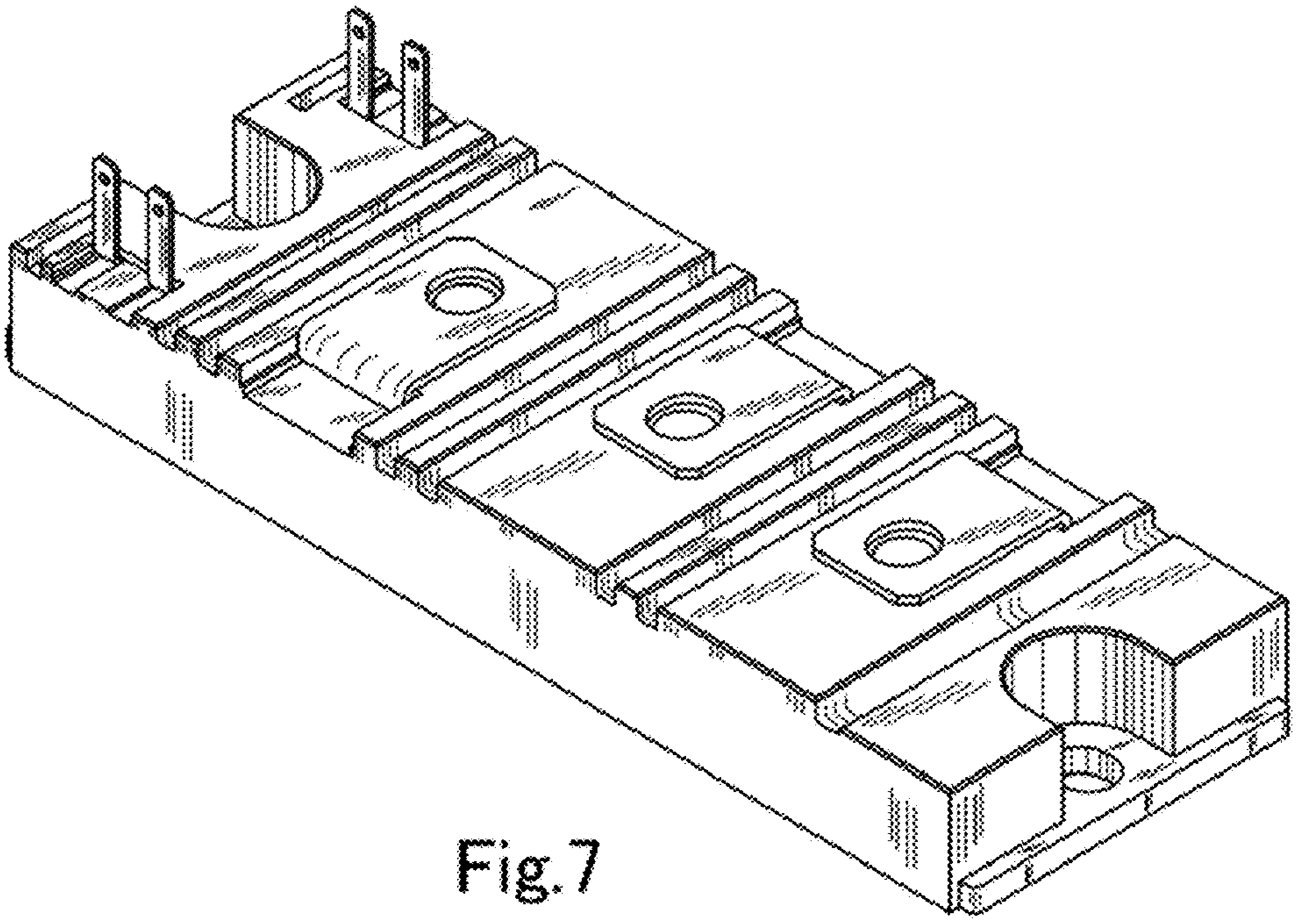

Fig.7